

# IGBT - Ultra Field Stop

## FGH40T120SQDNL4

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Ultra Field Stop Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co-packaged free wheeling diode with a low forward voltage.

### Features

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- These are Pb-Free Devices

### Typical Applications

- Solar Inverter
- Uninterruptible Power Inverter Supplies (UPS)
- Welding

### ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	$V_{CES}$	1200	V
Collector current @ $T_c = 25^{\circ}C$ @ $T_c = 100^{\circ}C$	$I_C$	160 40	A
Pulsed collector current, $T_{pulse}$ limited by $T_{Jmax}$	$I_{CM}$	160	A
Diode forward current @ $T_c = 25^{\circ}C$ @ $T_c = 100^{\circ}C$	$I_F$	160 40	A
Diode pulsed current, $T_{pulse}$ limited by $T_{Jmax}$	$I_{FM}$	160	A
Gate-emitter voltage Transient gate-emitter voltage ( $T_{pulse} = 5 \mu s$ , $D < 0.10$ )	$V_{GE}$	$\pm 20$ $\pm 30$	V
Power Dissipation @ $T_c = 25^{\circ}C$ @ $T_c = 100^{\circ}C$	$P_D$	454 227	W
Operating junction temperature range	$T_J$	-55 to +175	$^{\circ}C$
Storage temperature range	$T_{stg}$	-55 to +175	$^{\circ}C$
Lead temperature for soldering, 1/8" from case for 5 seconds	$T_{SLD}$	260	$^{\circ}C$

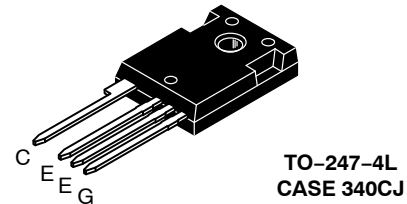
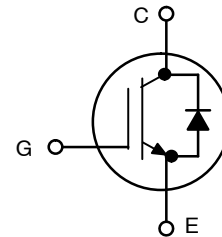
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



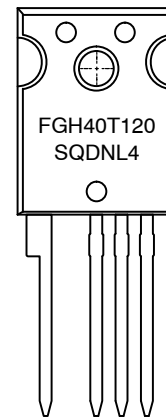
**ON Semiconductor**<sup>®</sup>

[www.onsemi.com](http://www.onsemi.com)

**40 A, 1200 V**  
 **$V_{CEsat} = 1.7 V$**   
 **$E_{off} = 1.1 mJ$**



### MARKING DIAGRAM



### ORDERING INFORMATION

Device	Package	Shipping
FGH40T120SQDNL4	TO-247 (Pb-Free)	30 Units / Rail

# FGH40T120SQDNL4

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{\theta JC}$	0.33	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-case, for Diode	$R_{\theta JC}$	0.61	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
-----------	-----------------	--------	-----	-----	-----	------

### STATIC CHARACTERISTIC

Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, I_C = 500\ \mu\text{A}$	$V_{(BR)CES}$	1200 1250*	-	-	V
Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 40\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 40\text{ A}, T_J = 175^{\circ}\text{C}$	$V_{CEsat}$	- -	1.78 2.3	1.95 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 400\ \mu\text{A}$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}$ $V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}, T_J = 175^{\circ}\text{C}$	$I_{CES}$	- -	- 0.6	0.4 -	mA
Gate leakage current, collector-emitter short-circuited	$V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$	$I_{GES}$	-	-	200	nA

\* Guaranteed by design.

Input capacitance	$V_{CE} = 20\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	$C_{ies}$	-	5000	-	pF
Output capacitance		$C_{oes}$	-	140	-	
Reverse transfer capacitance		$C_{res}$	-	80	-	
Gate charge total	$V_{CE} = 600\text{ V}, I_C = 40\text{ A}, V_{GE} = 15\text{ V}$	$Q_g$	-	221	-	nC
Gate to emitter charge		$Q_{ge}$	-	52	-	
Gate to collector charge		$Q_{gc}$	-	100	-	

### SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-on delay time	$T_J = 25^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 40\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 0\text{ to }15\text{ V}$	$t_{d(on)}$	-	46	-	ns
Rise time		$t_r$	-	33	-	
Turn-off delay time		$t_{d(off)}$	-	220	-	
Fall time		$t_f$	-	56	-	
Turn-on switching loss		$E_{on}$	-	1.4	-	mJ
Turn-off switching loss		$E_{off}$	-	1.1	-	
Total switching loss		$E_{ts}$	-	2.5	-	
Turn-on delay time	$T_J = 175^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 40\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 0\text{ to }15\text{ V}$	$t_{d(on)}$	-	47	-	ns
Rise time		$t_r$	-	33	-	
Turn-off delay time		$t_{d(off)}$	-	240	-	
Fall time		$t_f$	-	132	-	
Turn-on switching loss		$E_{on}$	-	2.7	-	mJ
Turn-off switching loss		$E_{off}$	-	1.8	-	
Total switching loss		$E_{ts}$	-	4.5	-	

### DIODE CHARACTERISTIC

Forward voltage	$V_{GE} = 0\text{ V}, I_F = 40\text{ A}$ $V_{GE} = 0\text{ V}, I_F = 40\text{ A}, T_J = 175^{\circ}\text{C}$	$V_F$	- -	3.4 3.1	3.8 -	V
Reverse recovery time	$T_J = 25^{\circ}\text{C}$ $I_F = 40\text{ A}, V_R = 400\text{ V}$ $di_F/dt = 500\text{ A}/\mu\text{s}$	$t_{rr}$	-	166	-	ns
Reverse recovery charge		$Q_{rr}$	-	0.78	-	$\mu\text{C}$
Reverse recovery current		$I_{rrm}$	-	9.0	-	A
Reverse recovery time	$T_J = 125^{\circ}\text{C}$ $I_F = 40\text{ A}, V_R = 400\text{ V}$ $di_F/dt = 500\text{ A}/\mu\text{s}$	$t_{rr}$	-	390	-	ns
Reverse recovery charge		$Q_{rr}$	-	4.0	-	$\mu\text{C}$
Reverse recovery current		$I_{rrm}$	-	20	-	A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# FGH40T120SQDNL4

## TYPICAL CHARACTERISTICS

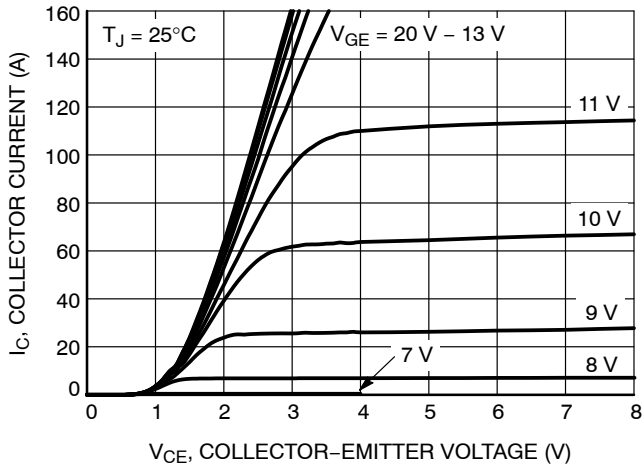


Figure 1. Output Characteristics

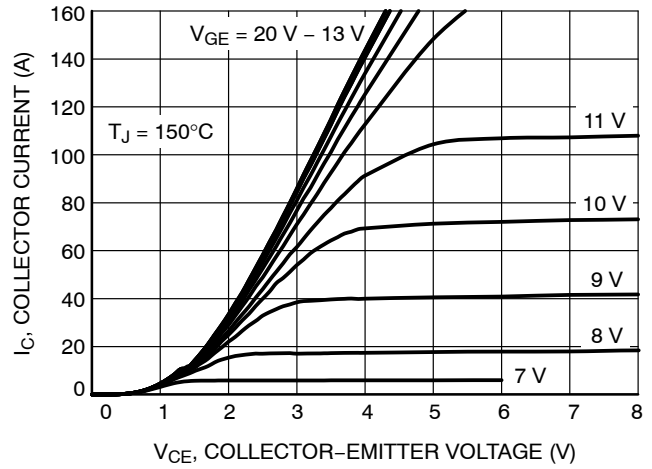


Figure 2. Output Characteristics

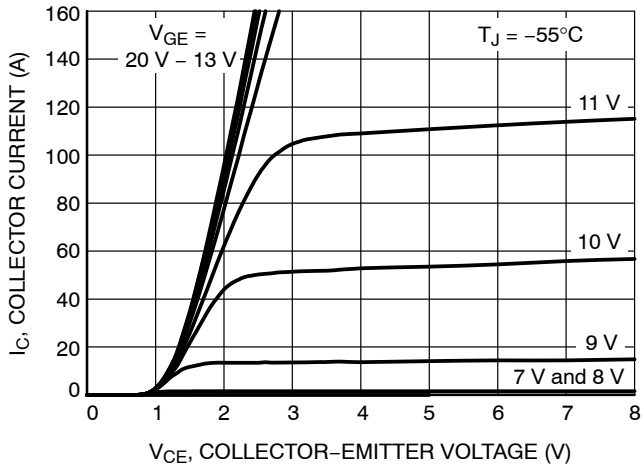


Figure 3. Output Characteristics

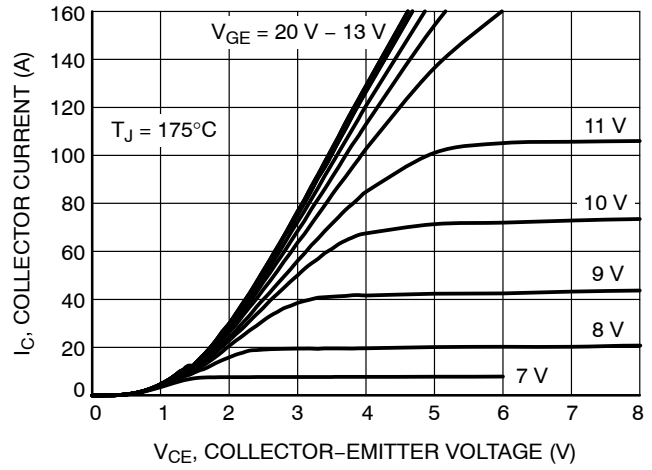


Figure 4. Output Characteristics

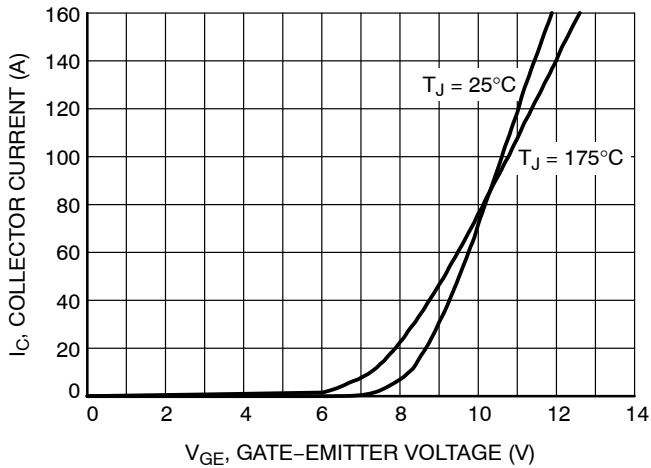


Figure 5. Typical Transfer Characteristics

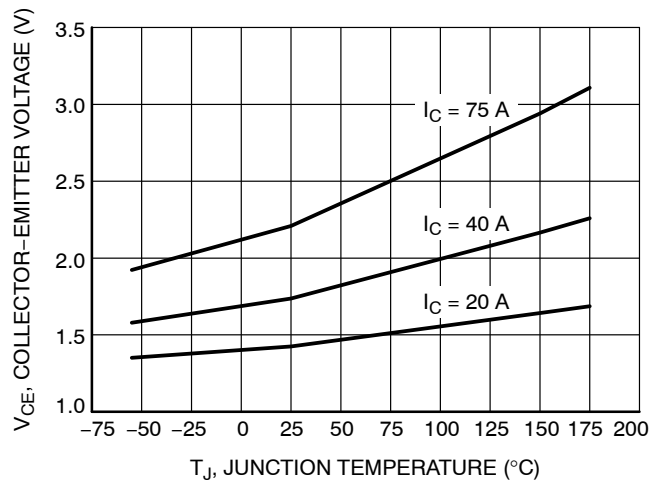


Figure 6.  $V_{CE(sat)}$  vs.  $T_J$

# FGH40T120SQDNL4

## TYPICAL CHARACTERISTICS

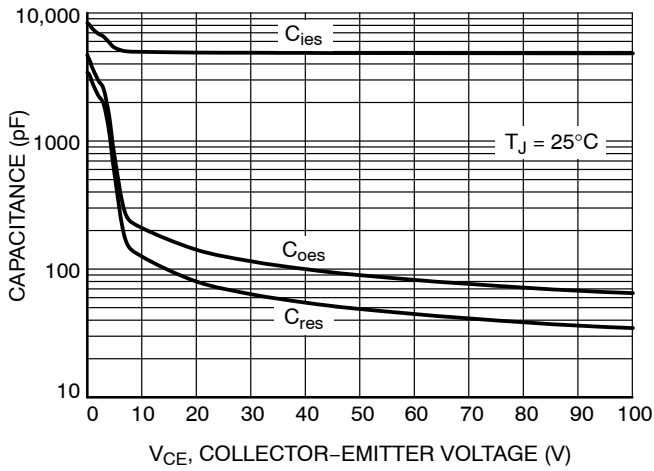


Figure 7. Typical Capacitance

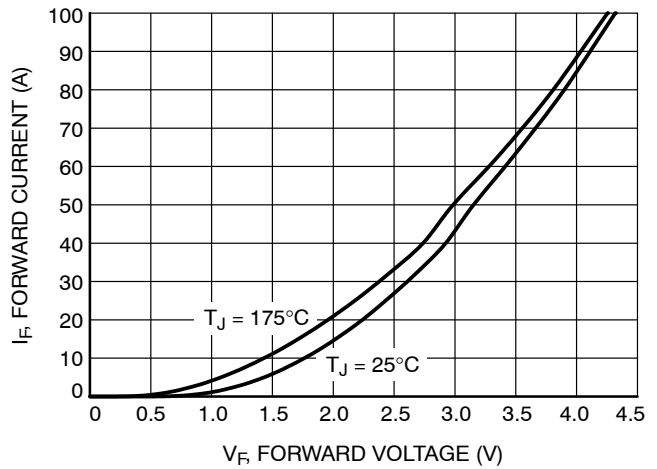


Figure 8. Diode Forward Characteristics

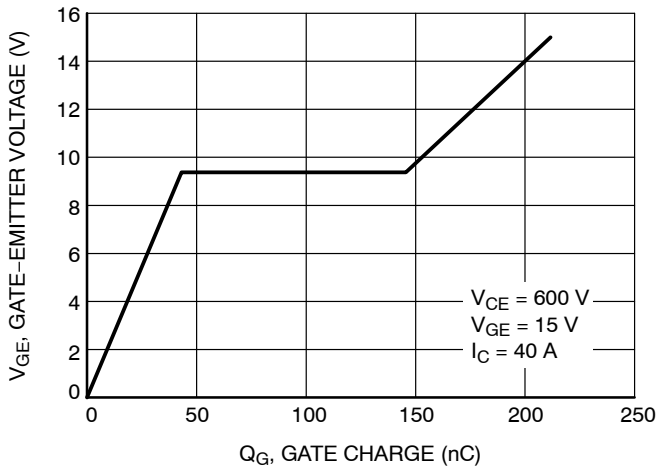


Figure 9. Typical Gate Charge

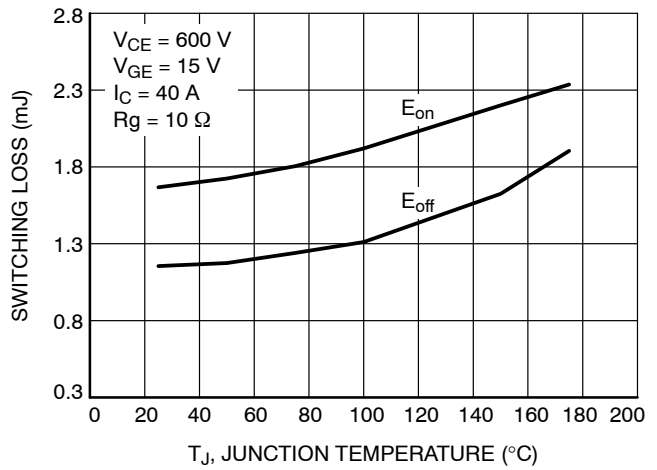


Figure 10. Switching Loss vs. Temperature

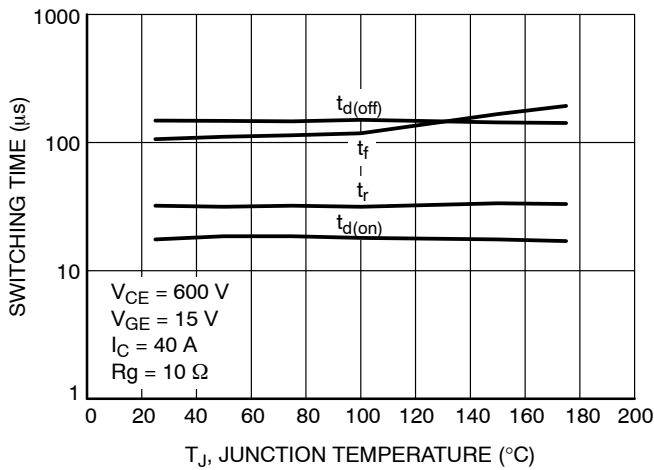


Figure 11. Switching Time vs. Temperature

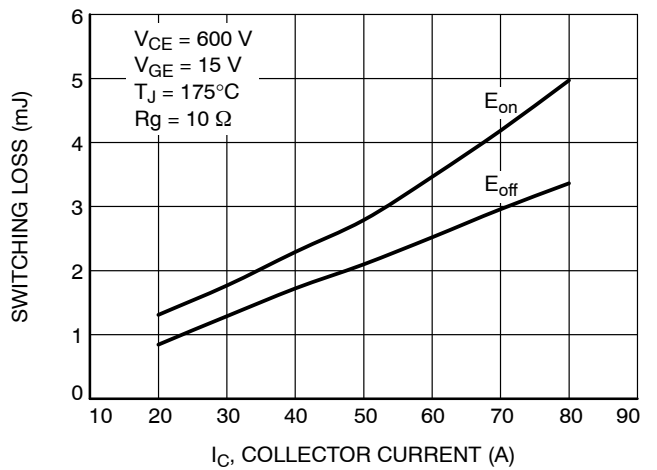


Figure 12. Switching Loss vs. IC

# FGH40T120SQDNL4

## TYPICAL CHARACTERISTICS

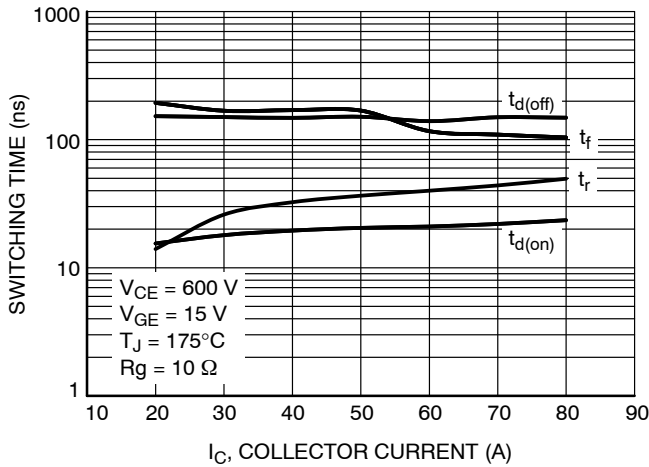


Figure 13. Switching Time vs. IC

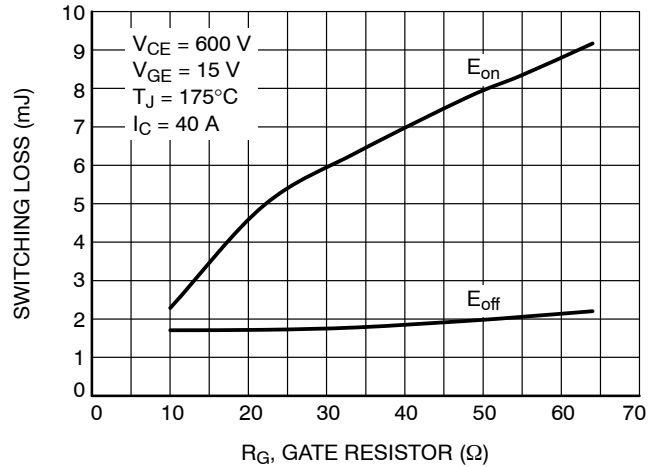


Figure 14. Switching Loss vs. RG

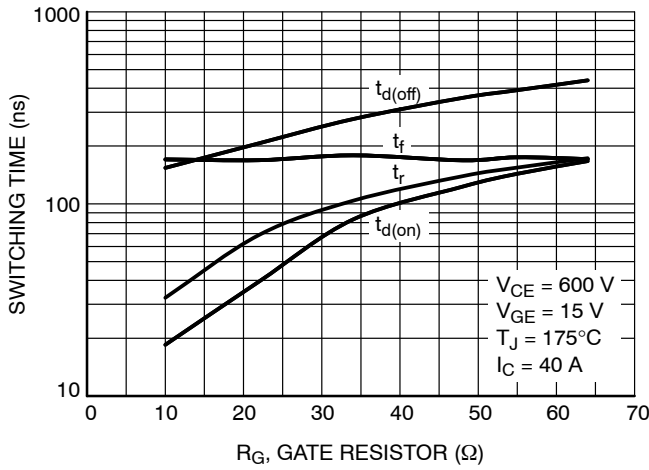


Figure 15. Switching Time vs. RG

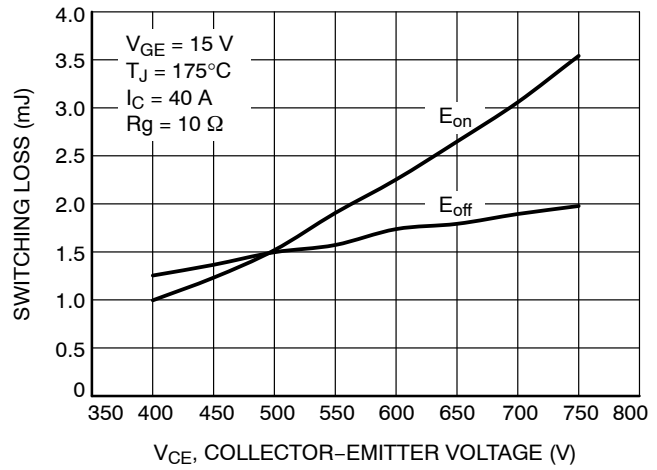


Figure 16. Switching Loss vs.  $V_{CE}$

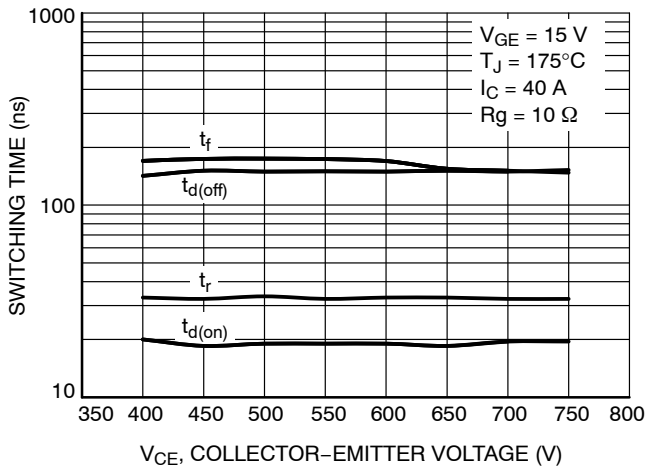


Figure 17. Switching Time vs.  $V_{CE}$

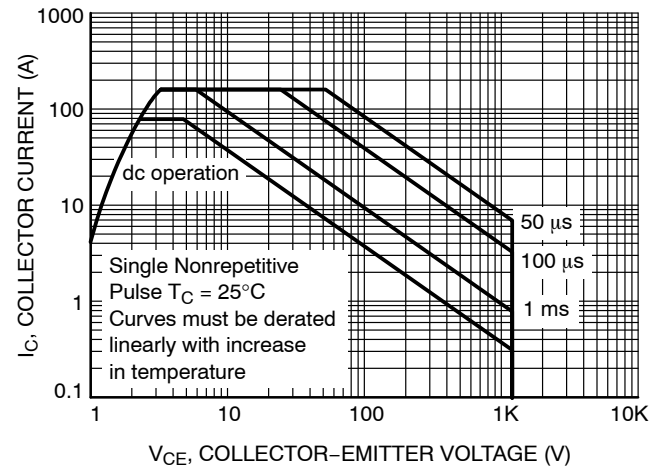


Figure 18. Safe Operating Area

# FGH40T120SQDNL4

## TYPICAL CHARACTERISTICS

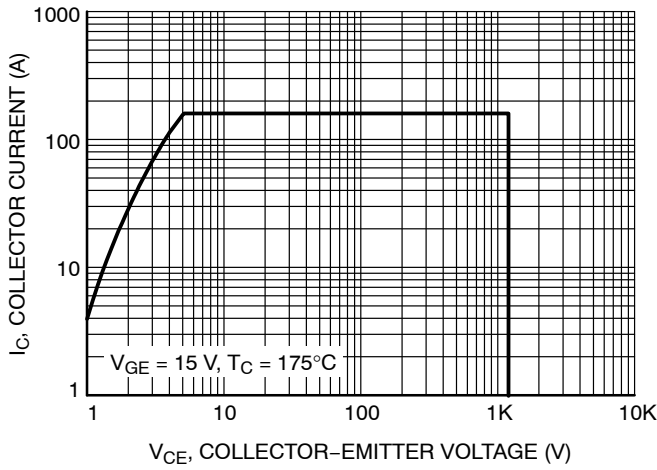


Figure 19. Reverse Bias Safe Operating Area

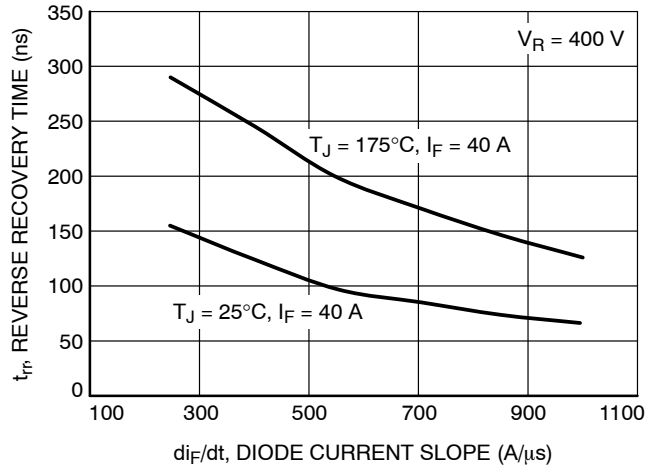


Figure 20.  $t_{rr}$  vs.  $di_F/dt$

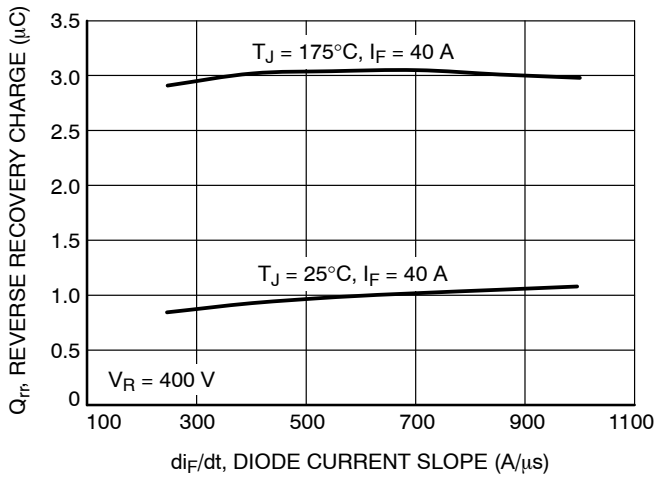


Figure 21.  $Q_{rr}$  vs.  $di_F/dt$

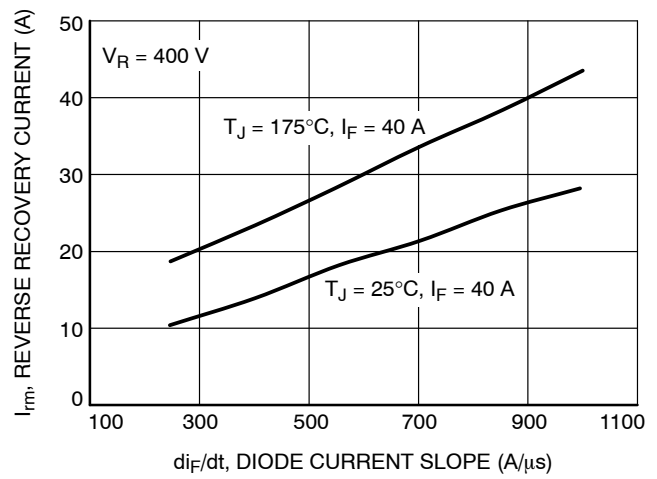


Figure 22.  $I_{rrm}$  vs.  $di_F/dt$

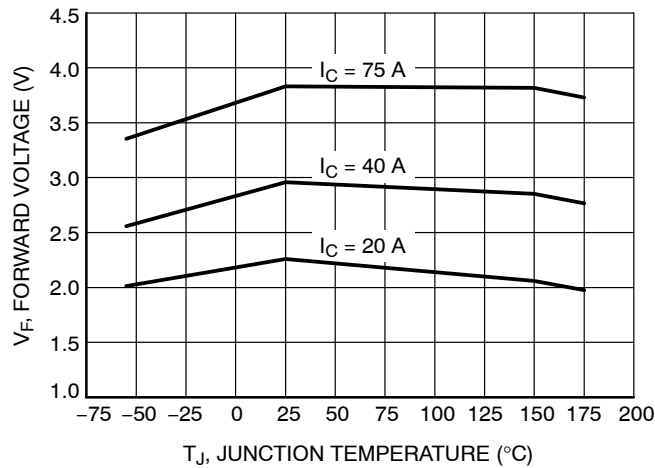


Figure 23.  $V_F$  vs.  $T_J$

# FGH40T120SQDNL4

## TYPICAL CHARACTERISTICS

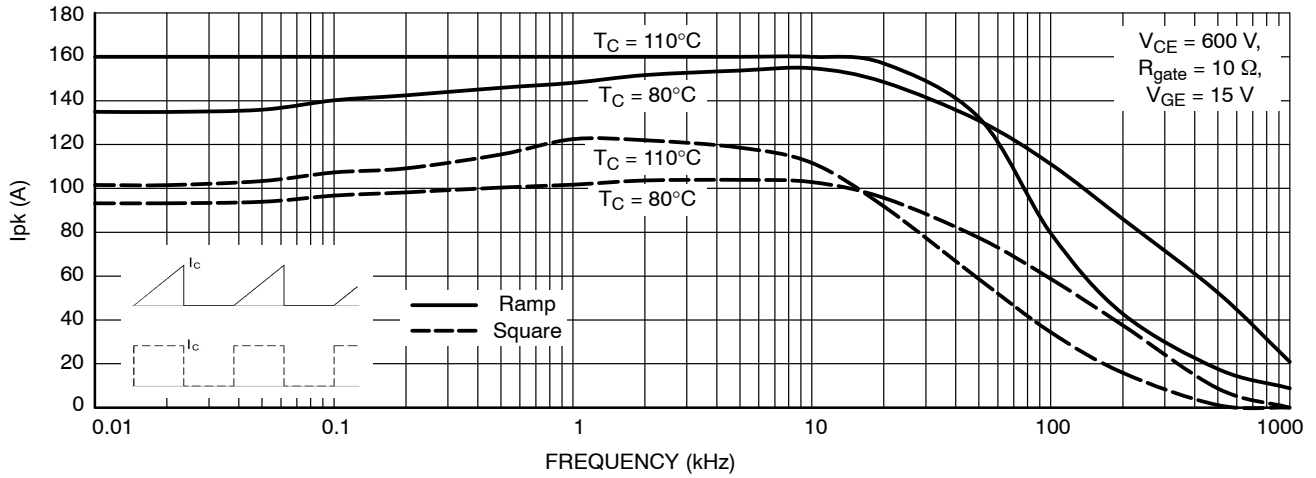


Figure 24. Collector Current vs. Switching Frequency

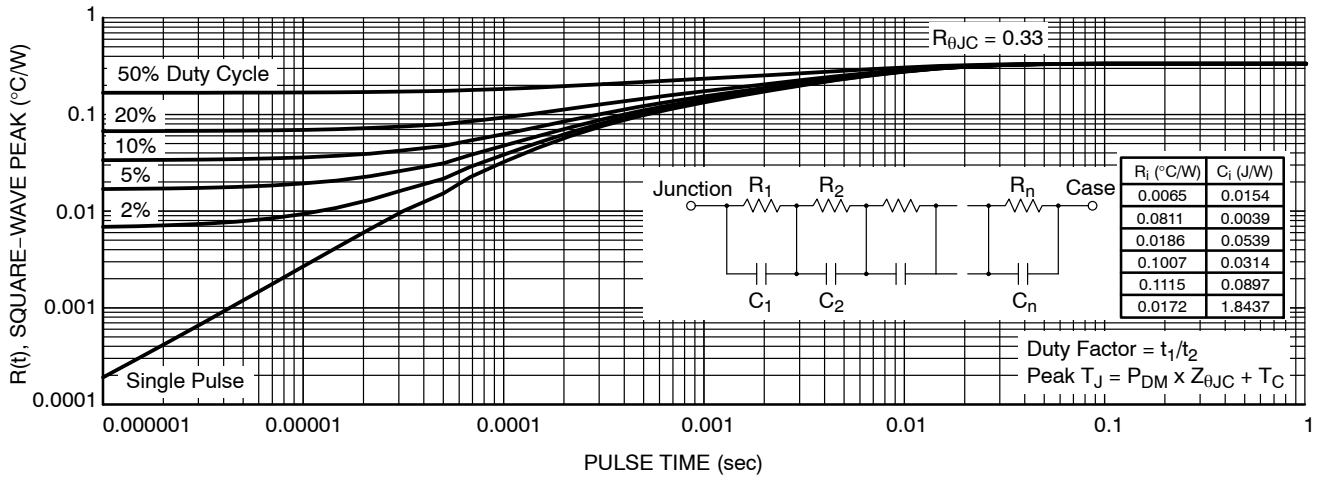


Figure 25. IGBT Transient Thermal Impedance

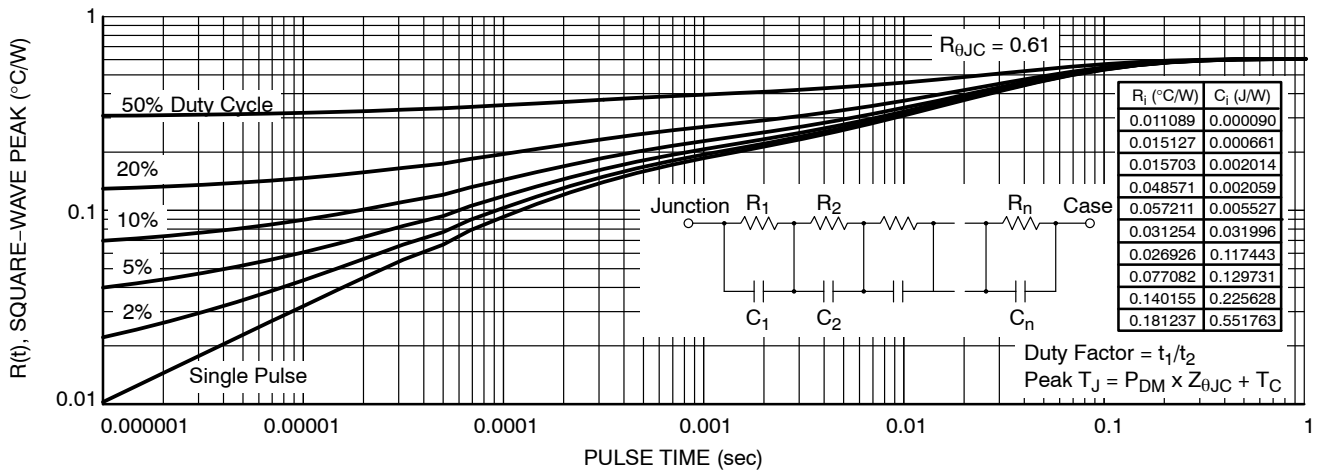


Figure 26. Diode Transient Thermal Impedance

# FGH40T120SQDNL4

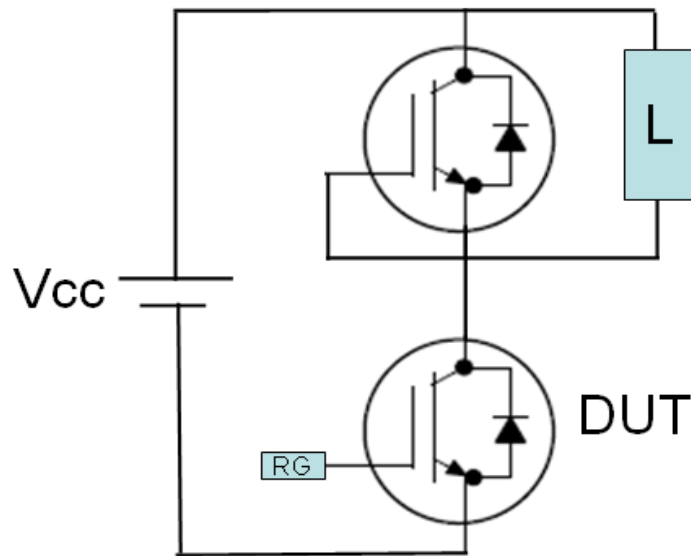


Figure 27. Test Circuit for Switching Characteristics

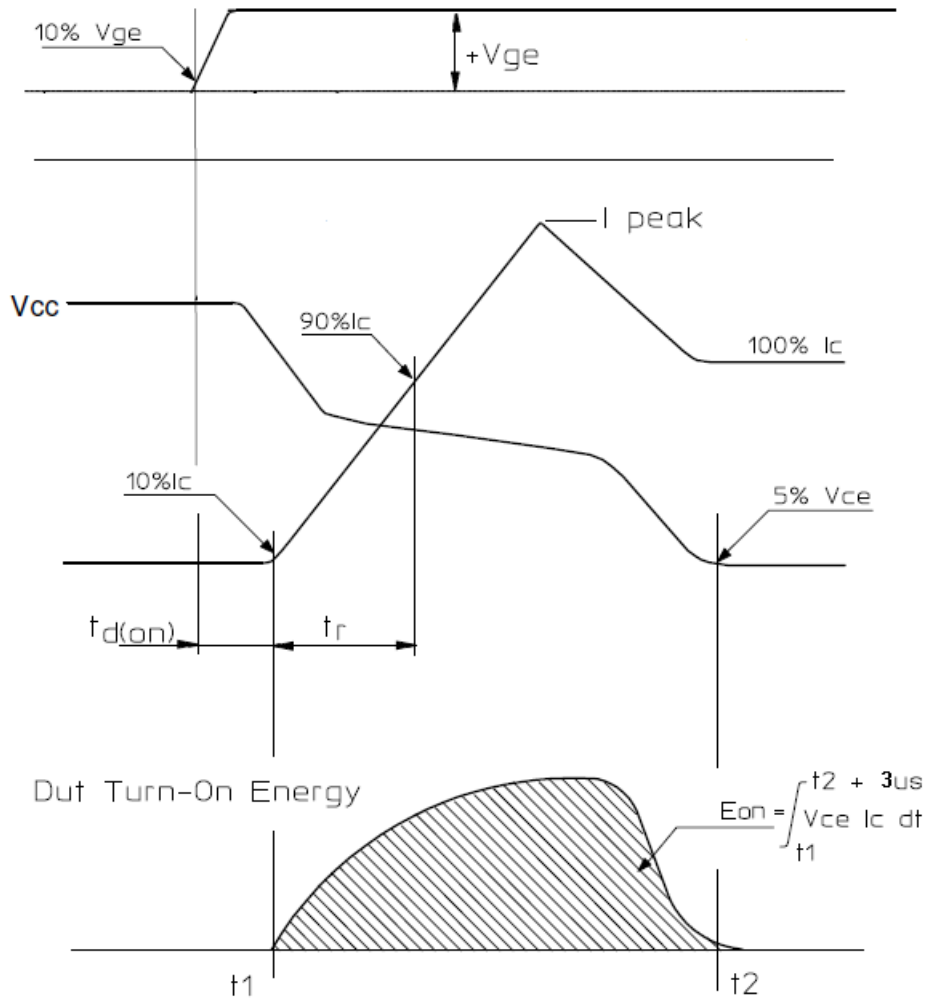


Figure 28. Definition of Turn On Waveform





Figure 29. Definition of Turn Off Waveform

# MECHANICAL CASE OUTLINE

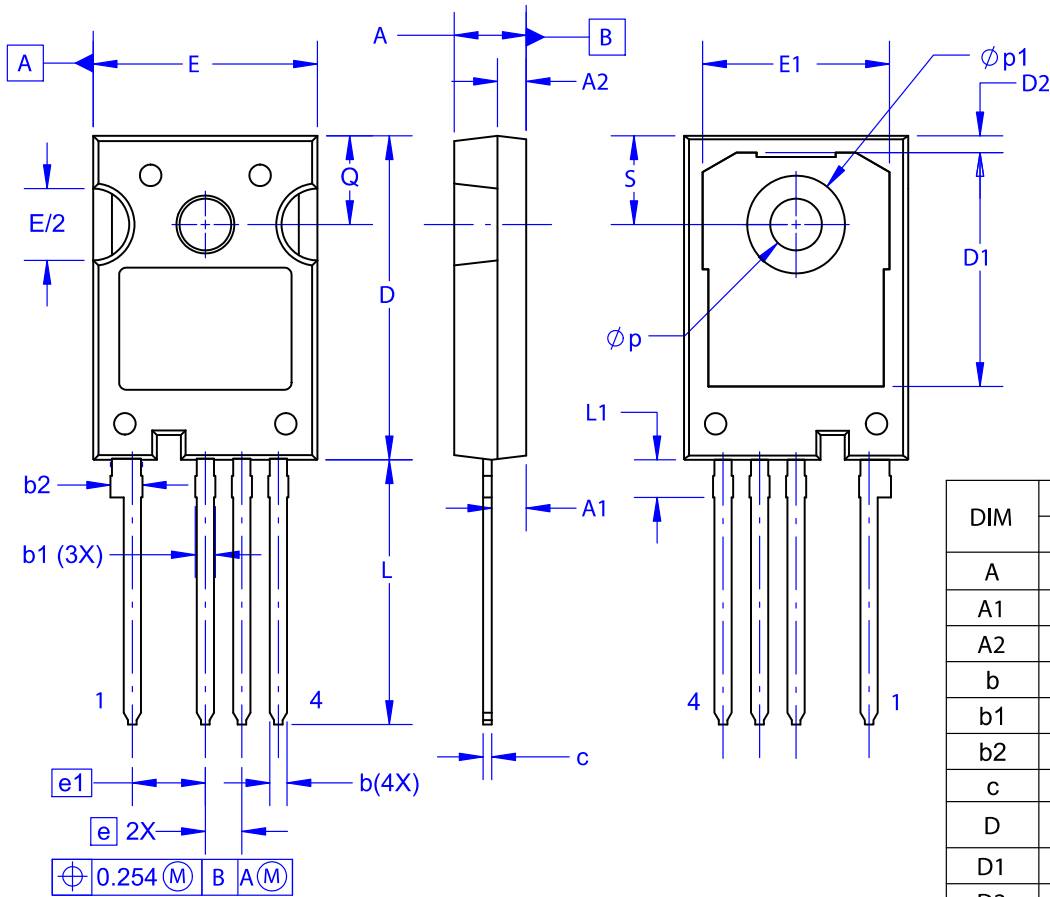
## PACKAGE DIMENSIONS

ON Semiconductor®



TO-247-4LD  
CASE 340CJ  
ISSUE A

DATE 16 SEP 2019



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b1	1.20	1.40	1.60
b2	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.25	16.50
D2	0.97	1.17	1.37
e	2.54 BSC		
e1	5.08 BSC		
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E/2	4.80	5.00	5.20
L	18.22	18.42	18.62
L1	2.42	2.62	2.82
p	3.40	3.60	3.80
p1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5-2009.

<b>DOCUMENT NUMBER:</b>	<b>98AON13852G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>TO-247-4LD</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.